(12)

(11) EP 2 206 746 A8

CORRECTED EUROPEAN PATENT APPLICATION

published in accordance with Art. 153(4) EPC

(15) Correction information:

Corrected version no 1 (W1 A1) Corrections, see Bibliography INID code(s) 71

(48) Corrigendum issued on: **18.08.2010 Bulletin 2010/33**

(43) Date of publication: **14.07.2010 Bulletin 2010/28**

(21) Application number: 08840790.3

(22) Date of filing: 27.10.2008

(51) Int CI.:

(86) International application number: PCT/JP2008/069406

(87) International publication number: WO 2009/054522 (30.04.2009 Gazette 2009/18)

(84) Designated Contracting States:

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

(30) Priority: 26.10.2007 JP 2007279374

(71) Applicant: AZ Electronic Materials USA Corp. Somerville, New Jersey 08876 (US)

(72) Inventor: OZAKI, Yuki Kakegawa-shi Shizuoka 437-1412 (JP)

(74) Representative: Rippel, Hans Christoph Isenbruck Bösl Hörschler Wichmann LLP Eastsite One Seckenheimer Landstrasse 4 68163 Mannheim (DE)

(54) COMPOSITION CONTAINING POLYSILAZANE COMPOUND, WHICH CAN PROVIDE DENSE SILICEOUS FILM

(57) The present invention provides a polysilazane-containing composition capable of forming a dense siliceous film more rapidly and at a lower temperature than known polysilazane-containing composition. In a process for forming the siliceous film, the composition comprising a polysilazane compound, a particular amine compound and a solvent is coated on a substrate and

converted into a siliceous substance. The particular amine compound preferably contains two amine groups separated from each other at the distance corresponding to five C-C bonds or more, and the amine groups preferably have hydrocarbon substituent groups.